PCN	PCN Number: 20201202001.1A PCN Date: Mar 10, 2021								
Title: Qualification of CDAT as an alternate AT site for Select Devices									
Customer Contact: PCN Manager Dept: Quality Services									
Proposed 1 st Ship Date: Mar. 2				2, 2021 Estimated Sample Date provided Sample requestions.			-		
Change Type:									
			Desig	ın		Wafe	r Bum	p Site	
Assembly Process			Data	Sheet				p Material	
Assembly Materials				Part number change Wafer Bump Proce			p Process		
Mechanical Specification Test S				Site		Wafei	/afer Fab Site		
	Packing/Shipping/Labeling Test Process Wafer Fab Materials							Materials	
☐ Wafer Fab Process									
				PC	N Details				
	cription of Ch								
Revision A is to announce the <u>addition</u> of new devices that were not included on the original PCN notification. These new devices are highlighted and bolded in the device list below. The expected first shipment date for these new devices will be 90 days from this notice for these newly added devices only. Texas Instruments Incorporated is announcing the qualification of CDAT as an additional AT site for the list of devices shown below. Construction differences are as follows.									
	Wha	it			Clark			CD	AT
	Mold Con	pound			4222790				3495
Rea	son for Chang	e:							
Sup	ply continuity								
Anti	icipated impa	ct on Fo	rm, Fit,	Functio	n, Quality or Relia	bilit	y (pos	itive	/ negative):
Non	e								
Anti			aterial [Anticipated impact on Material Declaration					
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			fro pro rep	nterial Decom produce oduction of the contraction o	clarations or Product ction data and will be release. Upon product be obtained at the s .ti.com/quality/docs	e ava iction ite li	nilable f n releas nk belo	follow se the ow	ing the e revised
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Product Affected:						
SN62825DMQR	TPS6282518DMQT	TPS6282618DMQR	TPS62826DMQT			
SN62826DMQR	TPS62825DMQR	TPS6282618DMQT	TPS62827DMQR			
SN62827DMQR	TPS62825DMQT	TPS62826DMQR	TPS62827DMQT			
TPS6282518DMQR						



TI Information Selective Disclosure

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device TPS6282xDMQ	Qual Device: TPS62903RPJR
HAST	Biased HAST, 130C/85%RH	96 hours	QBS	3/231/0
HBM	ESD - HBM	2000V	1/3/0	
HTOL	Life Test, 150C	300 hours	1/77/0	
HTSL	High Temp Storage Bake 150C	1000 hours	QBS	1/77/0
LU	Latch-up	85C	1/6/0	
SD	Solderability test	4 hours / 155C aging	1/22/0	
TC	Temperature Cycle, -65/150C	500 cycles	3/231/0	
UHAST	Unbiased HAST 130C/85%RH	96 hours	3/231/0	

- QBS: Qual By Similarity
- Qual Device TPS6282xDMQ is qualified at LEVEL1-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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